

#### APPLICATIONS

- Pulse Power
- Crowbars
- Ignitron Replacement

#### KEY PARAMETERS

$V_{DRM}$	4500V
$I_{T(AV)}$	760A
$I_{TSM}$	13000A
$di/dt$	5000A/ $\mu$ s

#### FEATURES

- Double Side Cooling
- Fast Turn-on
- Low Turn-on Losses

#### VOLTAGE RATINGS

Type Number	Repetitive Peak Voltages $V_{DRM} / V_{RRM}$	Conditions
PT40QPx45	4500/16	$T_{vj} = 0^\circ \text{ to } 125^\circ \text{C}$ , $I_{DRM} = I_{RRM} = 50\text{mA}$ , $V_{DRM}, V_{RRM} t_p = 10\text{ms}$

Lower voltage grades available.

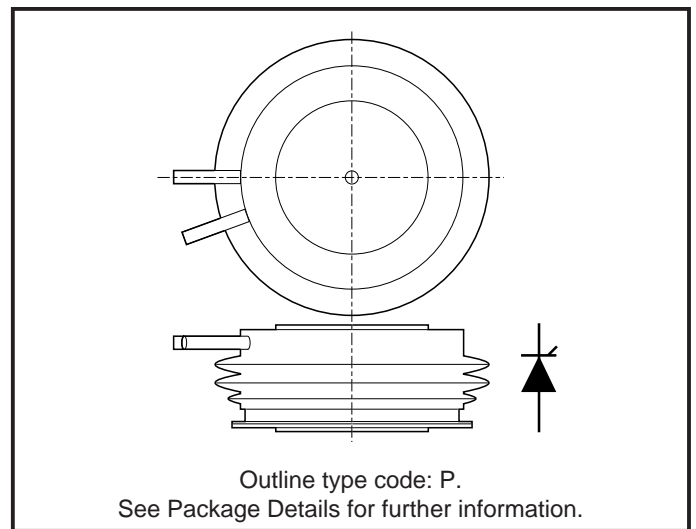


Fig.1 Package outline

#### CURRENT RATINGS

Symbol	Parameter	Conditions	Max.	Units
<b>Double Side Cooled</b>				
$I_{T(AV)}$	Mean on-state current	Half wave resistive load, $T_{case} = 80^\circ \text{C}$	760	A
$I_{T(RMS)}$	RMS value	$T_{case} = 80^\circ \text{C}$	1190	A

# PT40QPx45

## SURGE RATINGS

Symbol	Parameter	Conditions	Max.	Units
$I_{TSM}$	Surge (non-repetitive) on-state current	10ms half sine; $T_{case} = 125^{\circ}C$	10.4	kA
$I^2t$	$I^2t$ for fusing	$V_R = 50\% V_{RRM}$ - 1/4 sine	$541 \times 10^3$	$A^2s$
$I_{TSM}$	Surge (non-repetitive) on-state current	10ms half sine; $T_{case} = 125^{\circ}C$	13.0	kA
$I^2t$	$I^2t$ for fusing	$V_R = 0$	$845 \times 10^3$	$A^2s$

## THERMAL AND MECHANICAL DATA

Symbol	Parameter	Conditions	Min.	Max.	Units
$R_{th(j-c)}$	Thermal resistance - junction to case	Double side cooled dc	-	0.033	$^{\circ}C/W$
$R_{th(c-h)}$	Thermal resistance - case to heatsink	Clamping force 12.0kN with mounting compound Double side	-	0.008	$^{\circ}C/W$
$T_{vj}$	Virtual junction temperature	On-state (conducting)	-	135	$^{\circ}C$
		Reverse (blocking)	-	125	$^{\circ}C$
$T_{stg}$	Storage temperature range		-55	125	$^{\circ}C$
-	Clamping force		11.0	15.0	kN

## DYNAMIC CHARACTERISTICS

Symbol	Parameter	Conditions	Typ.	Max.	Units
$I_{RRM}/I_{DRM}$	Peak reverse and off-state current	At $V_{RRM}/V_{DRM}$ , $T_{case} = 125^{\circ}C$	-	50	mA
dV/dt	Maximum linear rate of rise of off-state voltage	To 67% $V_{DRM}$ , $T_j = 125^{\circ}C$ , $R_{gk} \leq 1.5\Omega$	-	200	$V/\mu s$
dI/dt	Rate of rise of on-state current	From 67% $V_{DRM}$ to 20kA Gate source 30A $t_r = 1.5\mu s$ , $T_j = 25^{\circ}C$ Non-repetitive	-	5000	$A/\mu s$
$V_{T(TO)}$	Threshold voltage	At $T_{vj} = 125^{\circ}C$	-	1.4	V
$r_T$	On-state slope resistance	At $T_{vj} = 125^{\circ}C$	-	0.152	m $\Omega$

## GATE TRIGGER CHARACTERISTICS AND RATINGS

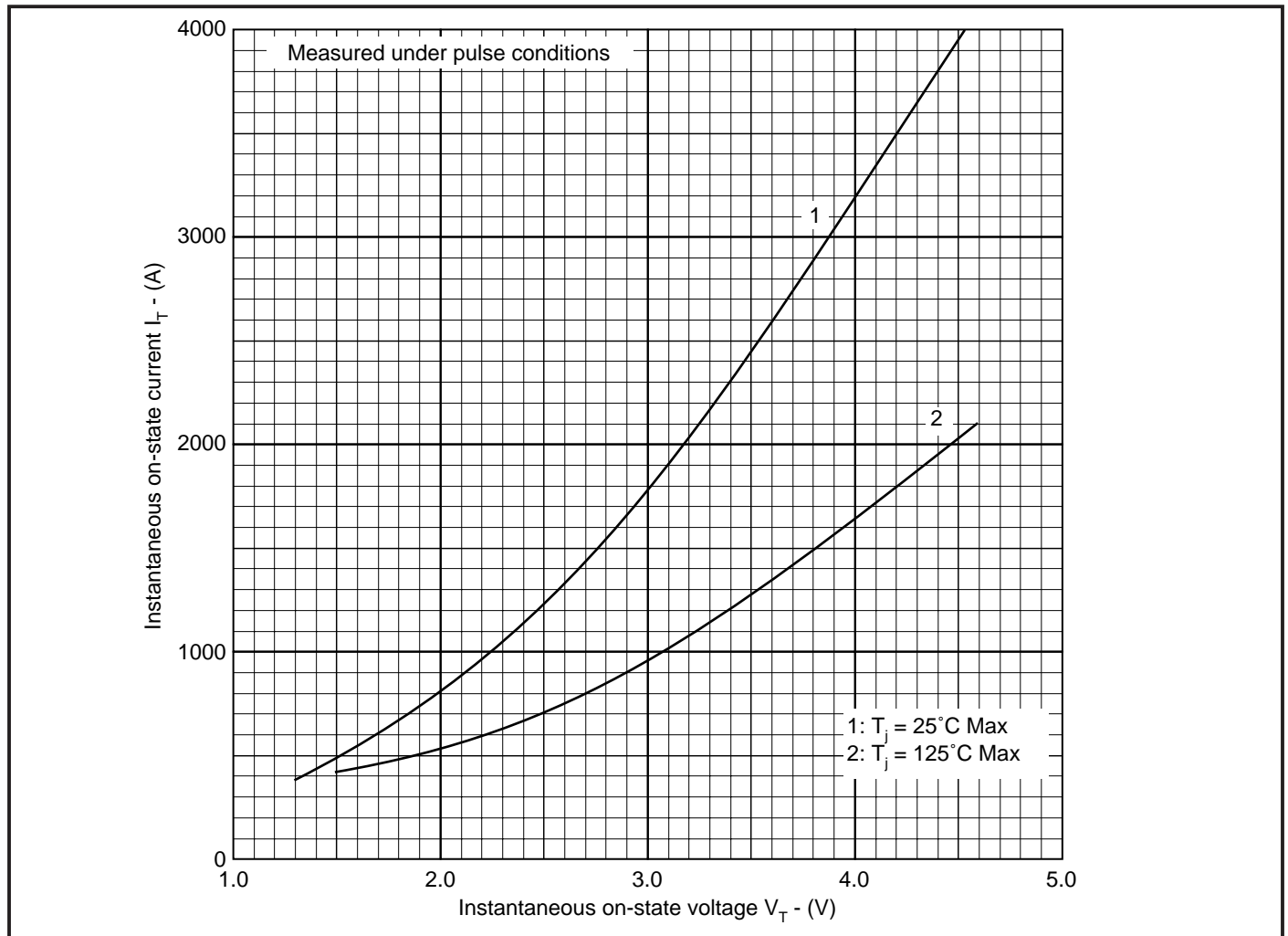
Symbol	Parameter	Conditions	Typ.	Max.	Units
$V_{GT}$	Gate trigger voltage	$V_{DRM} = 5V$ , $T_{case} = 25^{\circ}C$	1.0	4.0	V
$I_{GT}$	Gate trigger current	$V_{DRM} = 5V$ , $T_{case} = 25^{\circ}C$	-	1.5	A

**ORDERING INFORMATION**

PT Pulse Power Thyristor  
 40Q Device type  
 P Package outline type code  
 x lead length (see table, right)  
 45 Voltage x100

Lead length (x)		
O	No lead	
C	8"	200mm
D	10"	250mm
E	12"	300mm
F	16"	400mm
G	18"	450mm
H	20"	500mm
J	24"	600mm
K	30"	750mm
L	40"	1000mm

**CURVES**



**Fig.2 Maximum (limit) on-state characteristics**

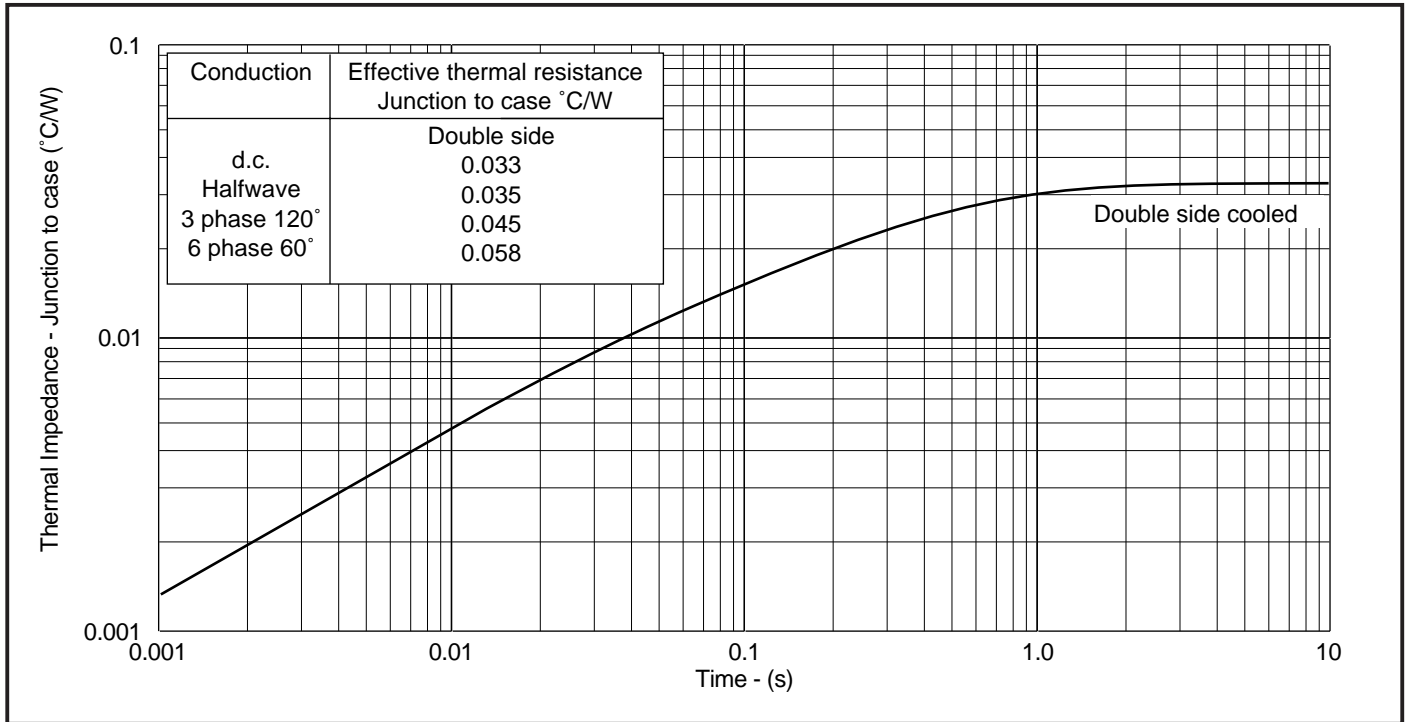
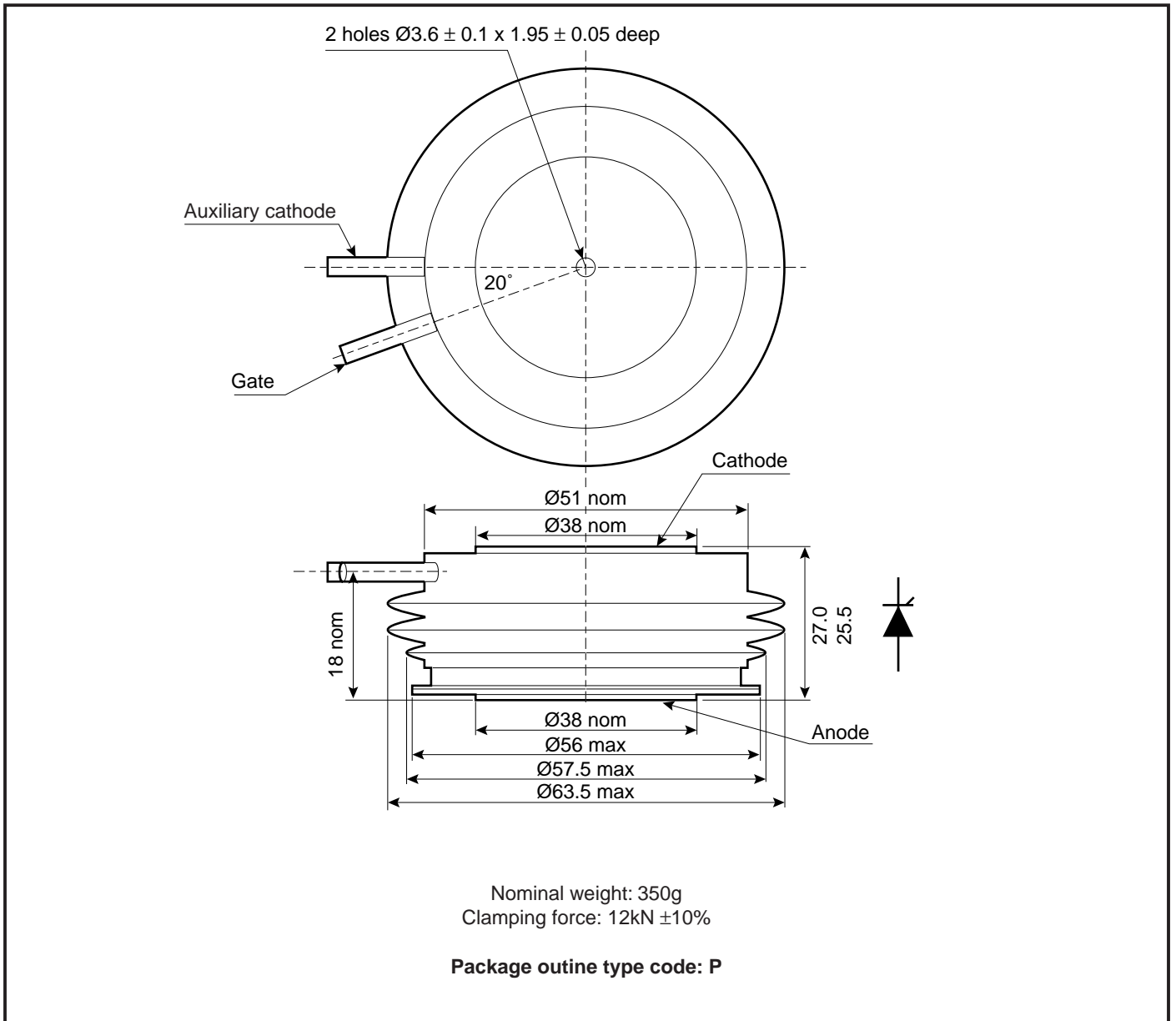


Fig.3 Maximum (limit) transient thermal impedance - junction to case

**PACKAGE DETAILS**

For further package information, please contact your local Customer Service Centre. All dimensions in mm, unless stated otherwise. DO NOT SCALE.



---

## POWER ASSEMBLY CAPABILITY

The Power Assembly group was set up to provide a support service for those customers requiring more than the basic semiconductor, and has developed a flexible range of heatsink and clamping systems in line with advances in device voltages and current capability of our semiconductors.

We offer an extensive range of air and liquid cooled assemblies covering the full range of circuit designs in general use today. The Assembly group offers high quality engineering support dedicated to designing new units to satisfy the growing needs of our customers.

Using the latest CAD methods our team of design and applications engineers aim to provide the Power Assembly Complete Solution (PACs).

## HEATSINKS

The Power Assembly group has its own proprietary range of extruded aluminium heatsinks which have been designed to optimise the performance of Dynex semiconductors. Data with respect to air natural, forced air and liquid cooling (with flow rates) is available on request.

For further information on device clamps, heatsinks and assemblies, please contact your nearest sales representative or Customer Services.

Stresses above those listed in this data sheet may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed.



<http://www.dynexsemi.com>

**e-mail: [power\\_solutions@dynexsemi.com](mailto:power_solutions@dynexsemi.com)**

---

HEADQUARTERS OPERATIONS  
**DYNEX SEMICONDUCTOR LTD**  
Doddington Road, Lincoln.  
Lincolnshire. LN6 3LF. United Kingdom.  
Tel: +44-(0)1522-500500  
Fax: +44-(0)1522-500550

CUSTOMER SERVICE  
Tel: +44 (0)1522 502753 / 502901. Fax: +44 (0)1522 500020

© Dynex Semiconductor 2003 TECHNICAL DOCUMENTATION – NOT FOR RESALE. PRODUCED IN UNITED KINGDOM

---

This publication is issued to provide information only which (unless agreed by the Company in writing) may not be used, applied or reproduced for any purpose nor form part of any order or contract nor to be regarded as a representation relating to the products or services concerned. No warranty or guarantee express or implied is made regarding the capability, performance or suitability of any product or service. The Company reserves the right to alter without prior notice the specification, design or price of any product or service. Information concerning possible methods of use is provided as a guide only and does not constitute any guarantee that such methods of use will be satisfactory in a specific piece of equipment. It is the user's responsibility to fully determine the performance and suitability of any equipment using such information and to ensure that any publication or data used is up to date and has not been superseded. These products are not suitable for use in any medical products whose failure to perform may result in significant injury or death to the user. All products and materials are sold and services provided subject to the Company's conditions of sale, which are available on request.

All brand names and product names used in this publication are trademarks, registered trademarks or trade names of their respective owners.